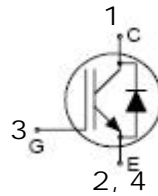


**PRELIMINARY DATASHEET**
**IGBT in Trench & Field Stop technology with soft, fast recovery anti-parallel diode, in Isolated SOT227 Package**

- High switching speed
- Low  $V_{CE(sat)}$
- Short circuit withstand time – 5  $\mu$ s
- Designed for frequency converters and UPS
- Very tight parameter distribution
- High ruggedness, temperature stability
  - parallel switching capability
- Very soft, fast recovery anti-parallel diode
- Pb-free lead finish; RoHS compliant


**MAXIMUM RATINGS**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

Parameter	Symbol	Value	Units
Collector-emitter voltage	$V_{CE}$	600	V
DC collector current, limited by $T_{jmax}$ $T_C = 25^\circ\text{C}$ $T_C = 80^\circ\text{C}$	$I_C$	150 75	A
Pulsed collector current, $t_p$ limited by $T_{jmax}$	$I_{Cpulse}$	225	
Turn off safe operating area $V_{CE} \leq 600\text{V}$ , $T_j \leq 150^\circ\text{C}$	-	225	
Diode forward current $T_C = 25^\circ\text{C}$ $T_C = 80^\circ\text{C}$	$I_F$	120 75	
Diode pulsed current, $t_p$ limited by $T_{jmax}$	$I_{Fpulse}$	225	
Gate-emitter voltage	$V_{GE}$	$\pm 20$	V
Short circuit withstand time <sup>1</sup> $V_{GE} = 15\text{V}$ , $V_{CC} \leq 400\text{V}$ , $T_j \leq 150^\circ\text{C}$	$t_{SC}$	5	$\mu\text{s}$
Soldering temperature Wave soldering, 1.6 mm (0.063 in.) from case for 10s	$T_S$	260	$^\circ\text{C}$
Operating junction and storage temperature	$T_j, T_{stg}$	-55... +175	$^\circ\text{C}$

**Thermal and Isolation Characteristics**

Parameter	Symbol	Max. Value	Units
<b>Characteristics</b>			
IGBT thermal resistance, junction to case	$R_{thJC}$	0.46	K/W
Diode thermal resistance, junction to case	$R_{thJCD}$	0.78	
Thermal resistance, junction to ambient	$R_{thJA}$	40	
Isolation voltage, RMS (measured between terminals and mounting base, 50-60 Hz, for 1-3 seconds)	$V_{iso}$	3000	V

<sup>1</sup> Allowed number of short circuits: < 1000; time between short circuits: > 1s.

CAUTION: These devices are ESD sensitive. Use proper handling procedure.

**ELECTRICAL CHARACTERISTICS**, at  $T_j = 25^\circ\text{C}$ , unless otherwise specified

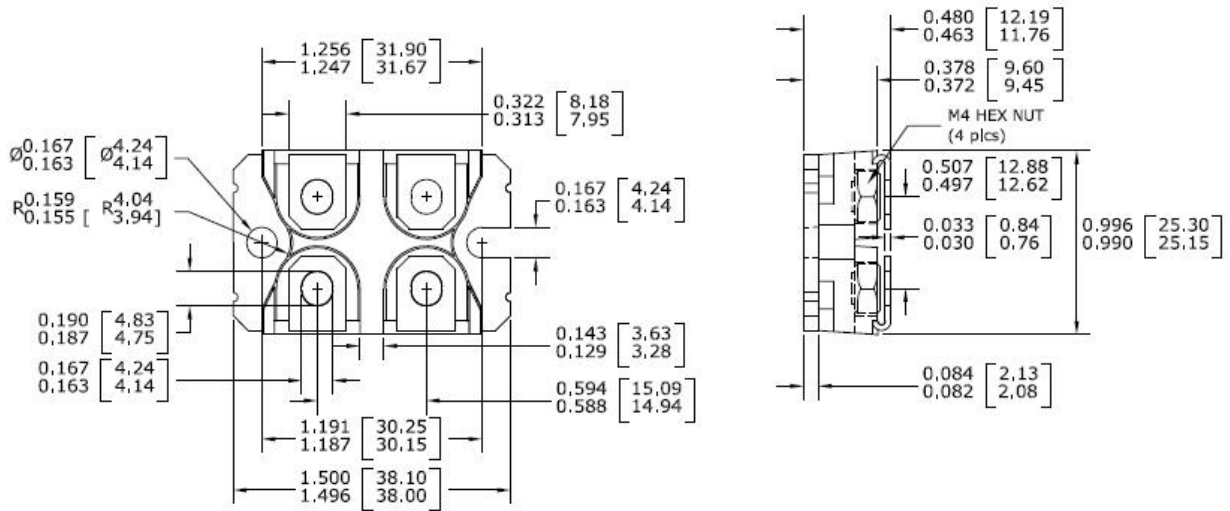
Parameter	Symbol	Conditions	Value			Unit
			Min.	Typ.	Max.	
<b>Static Characteristics</b>						
Collector-emitter breakdown voltage	$V_{(BR)CES}$	$V_{GE} = 0V, I_C = 0.2mA$	600	-	-	V
Collector-emitter saturation voltage	$V_{CE(sat)}$	$V_{GE} = 15V, I_C = 75A$ $T_j = 25^\circ\text{C}$ $T_j = 175^\circ\text{C}$	- -	1.5 1.9	2.0 -	
Diode forward voltage	$V_F$	$V_{GE} = 0V, I_F = 75A$ $T_j = 25^\circ\text{C}$ $T_j = 175^\circ\text{C}$	- -	1.65 1.6	2.0 -	
Gate-emitter threshold voltage	$V_{GE(th)}$	$I_C = 1.2mA, V_{CE} = V_{GE}$	4.1	4.9	5.7	
Zero gate voltage collector current	$I_{CES}$	$V_{CE} = 600V, V_{GE} = 0$ $T_j = 25^\circ\text{C}$ $T_j = 150^\circ\text{C}$	- -	- -	40 1000	$\mu\text{A}$
Gate-emitter leakage current	$I_{GES}$	$V_{CE} = 0V, V_{GE} = 20V$	-	-	100	nA
Transconductance	$g_{fs}$	$V_{CE} = 20V, I_C = 75A$	-	41	-	S
<b>Dynamic Characteristics</b>						
Input capacitance	$C_{iss}$	$V_{CE} = 25V,$ $V_{GE} = 0V,$ $f = 1\text{MHz}$	-	4620	-	pF
Output capacitance	$C_{oss}$		-	288	-	
Reverse transfer capacitance	$C_{riss}$		-	137	-	
Gate charge	$Q_{Gate}$	$V_{CC} = 480V, I_C = 75A$ $V_{GE} = 15V$	-	470	-	nC
Internal emitter inductance measured 5mm (0,197 in.) from case	$L_E$		-	13	-	nH
Short circuit collector current <sup>1</sup>	$I_{C(SC)}$	$V_{GE} = 15V, t_{SC} \leq 5 \mu\text{s}$ $V_{CC} \leq 600V,$ $T_j = 150^\circ\text{C}$	-	690	-	A

**SWITCHING CHARACTERISTICS, Inductive Load** at  $T_j = 25^\circ\text{C}$ 

Parameter	Symbol	Conditions	Value			Unit	
			Min.	Typ.	Max.		
<b>IGBT Characteristics</b>							
Turn-on delay time	$t_{d(on)}$	$T_j = 25^\circ\text{C},$ $V_{CC} = 400V, I_C = 75A,$ $V_{GE} = 0/15V,$ $R_G = 5\Omega,$ $L_G^2 = 100\text{nH},$ $C_G^2 = 39\text{pF}$ Energy losses include tail and diode reverse recovery.	-	33	-	ns	
Rise time	$t_r$		-	36	-		
Turn-off delay time	$t_{d(off)}$		-	330	-		
Fall time	$t_f$		-	35	-		
Turn-on energy	$E_{on}$		Energy losses include tail and diode reverse recovery.	-	2.0	-	mJ
Turn-off energy	$E_{off}$			-	2.5	-	
Total switching energy	$E_{ts}$			-	4.5	-	
<b>Anti-Parallel Diode Characteristics</b>							
Diode reverse recovery time	$t_{rr}$	$T_j = 25^\circ\text{C},$	-	264	-	ns	
Diode reverse recovery charge	$Q_{rr}$	$V_R = 300V, I_F = 75A,$	-	908	-	nC	
Diode peak reverse recovery current	$I_{rrm}$	$di/dt = 200A/\mu\text{s}$	-	8.3	-	A	

<sup>1</sup> Allowed number of short circuits: < 1000; time between short circuits: > 1s.  
<sup>2</sup> Leakage inductance  $L_G$  and Stray capacity  $C_G$  due to dynamic test circuit.

**Package Outline Drawing**



CAUTION: These devices are ESD sensitive. Use proper handling procedure.

**Disclaimer**

These specifications may not be considered as a guarantee of components characteristics. Components have to be tested depending on intended application as adjustments may be necessary. The use of **iQXPRZ Power Inc.** components in life support appliances and systems are subject to written approval of **iQXPRZ Power Inc.**